

SPECIAL FEATURES

TEC-BOND 214/12 has been formulated to have a short open-time and a high molten tack. The viscosity has been positioned to prevent soaking in on very porous carton board, thus giving better yielding. A high molten tack reduces the chance of a carton opening up when a 'springy' carton board is used. TECBOND 214/12 also has a high seal resistance which enables it to resist temperatures encountered in heat shrink tunnels as well as other high ambient temperatures.

PHYSICAL FORM

Quoted Nominal 12mm dia.
Actual 11.5mm + 0.2mm
Length 300mm
Approx 34 Sticks/Kilo

PACKAGING

Packed in 5kg TEC-BOND Cartons.
500kg/pallet.
L -1200 W -1000 H- 920mm including pallet.

Further information is always available to help solve your adhesive problems. Should you require any further information on our adhesives or applicators please contact your local distributor (Name and address below).

The information contained on this data sheet is for guidance only. It is the result of careful laboratory evaluations by trained and qualified staff using British Standard or similar test methods. However, no warranty is expressed or implied regarding the accuracy of this data or the suitability of the adhesive for any specific purpose. In every case we strongly recommend that the user shall make their own tests to determine to their own satisfaction the suitability of the adhesive for their particular purpose. Neither seller or manufacturer shall be liable for any injury, loss, damage. Direct or consequential arising out of the use or inability to use the product.

HEALTH AND SAFETY

Take normal precautions when using hot liquids as molten adhesive temperatures range from 150°C - 220°C.

BURNS: Immediately cool affected area with cold water. Do not remove cold adhesive from skin, seek medical attention.

FUMES: Do not inhale. Use in a well ventilated area.

FIRES: Not normally a hazard but in a fire hotmelts are combustible, use dry powder or CO² Extinguishers.

DO NOT USE WATER.

THERMAL STABILITY

All our hotmelt adhesives are formulated to minimise the risk of degradation at elevated temperatures. To ensure clear running keep to the suggested application temperature.

(See Typical Performance)

STORAGE

Store in a clean dry place at temperatures between 5 and 30°C with boxes closed. Do not expose to direct sunlight and use oldest stock first.

POWER ADHESIVES

HOTMELT TECHNICAL DATA

TEC-BOND 214/12

GENERAL DESCRIPTION

TEC-BOND 214/12 is a high quality fast setting EVA based Hotmelt formulated for packaging.

Recommended for use on paper and board substrates.

SUITABLE APPLICATORS

HOTFIX 180

TEC 200

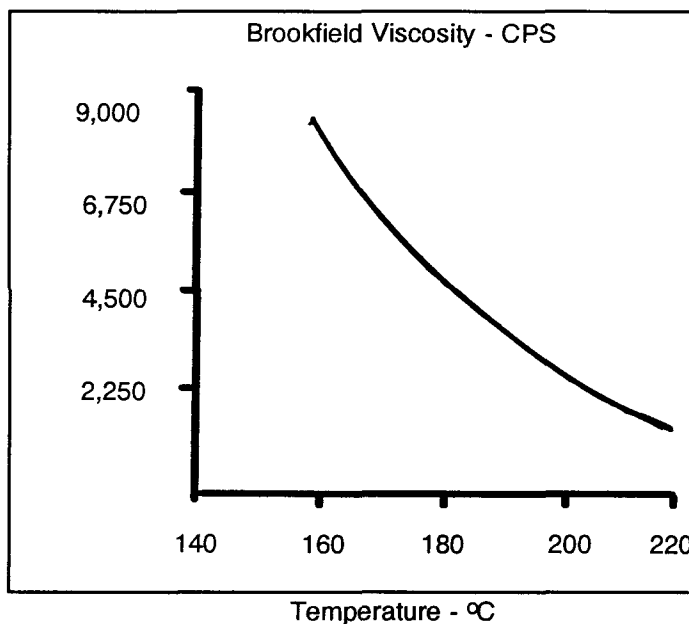
TEC 601

TEC 700

TEC 901

and most other 12mm Hotmelt Glue Applicators

TEMPERATURE - VISCOSITY



TYPICAL PERFORMANCE DATA

Adhesive Type:

Synthetic polymer based hotmelt.

Colour:

Light Brown

Brookfield Viscosity (ASTM D3236):

160°C - 8,350 c.p.s

180°C - 4,550 c.p.s.

200°C - 2,800 c.p.s.

220 °C - 1,800 c.p.s.

Also see graph.

Ring & Ball Softening Point (ASTM E28):

96°C

Heat Resistance (BS5350 Part H3):

70°C

Open Time: (BS5350 Part H4):

15 secs.

Suggested Application Temperature:

160-200°C

Molten Tack:

High

All constituent parts of this adhesive have been approved by the American F.D.A. under the following Section:-

C.F.R.21 175-105 Adhesive.